

Features

- Trench MV MOSFET Technology
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

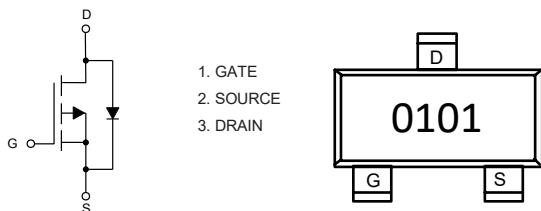
- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature: -55°C to +150°C
- Thermal Resistance: 162°C/W Junction to Ambient (Note2)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	-100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	-1	A
$T_A=100^\circ\text{C}$		-0.63	
Pulsed Drain Current ^(Note3)	I_{DM}	-4	A
Total Power Dissipation ^(Note4)	P_D	0.77	W

Note:

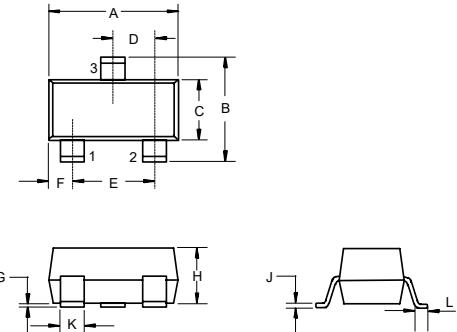
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of $R_{\text{th}JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction-ambient thermal resistance.

Internal Structure and Marking Code



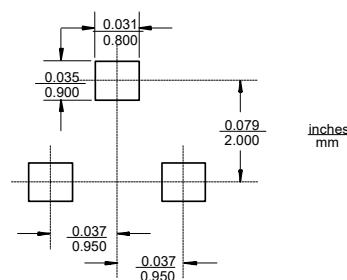
P-Channel MOSFET

SOT-23



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.110	0.120	2.80	3.04	
B	0.083	0.104	2.10	2.64	
C	0.047	0.055	1.20	1.40	
D	0.034	0.041	0.85	1.05	
E	0.067	0.083	1.70	2.10	
F	0.018	0.024	0.45	0.60	
G	0.0004	0.006	0.01	0.15	
H	0.035	0.043	0.90	1.10	
J	0.003	0.007	0.08	0.18	
K	0.012	0.020	0.30	0.51	
L	0.007	0.020	0.20	0.50	

Suggested Solder Pad Layout



Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-100			V
Gate-Source Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-100V, V_{GS}=0V$			-1	μA
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.5	-2.2	-3.0	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-1.0A$		560	800	$m\Omega$
		$V_{GS}=-4.5V, I_D=-0.5A$		620	1000	
Gate Resistance	R_G	$f=1\text{ MHz}, \text{Open drain}$		4.6		Ω
Forward Tranconductance	g_{FS}	$V_{DS}=-5V, I_D=-1A$		5		s
Diode Characteristics						
Continuous Body Diode Current	I_S				-1	A
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=-1A$			-1.2	V
Reverse Recovery Time	t_{rr}	$I_F=-1A, dI_F/dt=100A/\mu s$		28		ns
Reverse Recovery Charge	Q_{rr}			40		nC
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=-40V, V_{GS}=0V, f=1MHz$		342		pF
Output Capacitance	C_{oss}			18.3		
Reverse Transfer Capacitance	C_{rss}			14.3		
Total Gate Charge	Q_g	$V_{DS}=-10V, V_{GS}=-10V, I_D=-1A$		7.8		nC
Gate-Source Charge	Q_{gs}			1.5		
Gate-Drain Charge	Q_{gd}			0.98		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=-10V, V_{GS}=-10V, R_{GEN}=2.5\Omega, I_D=-1A$		6.1		ns
Turn-On Rise Time	t_r			2.7		
Turn-Off Delay Time	$t_{d(off)}$			12		
Turn-Off Fall Time	t_f			3.8		

Curve Characteristics

Fig.1 - Typical Output Characteristics

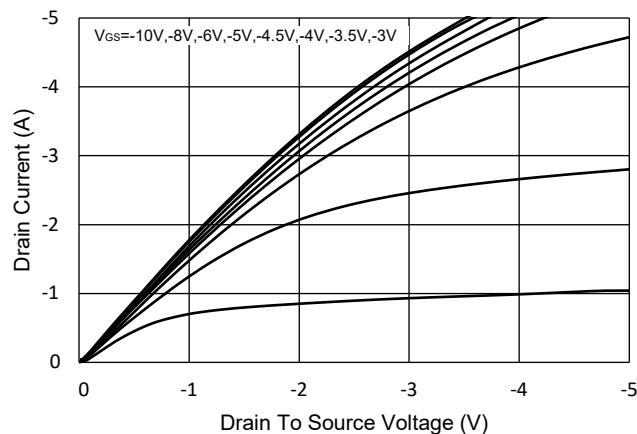


Fig.2 - Transfer Characteristic

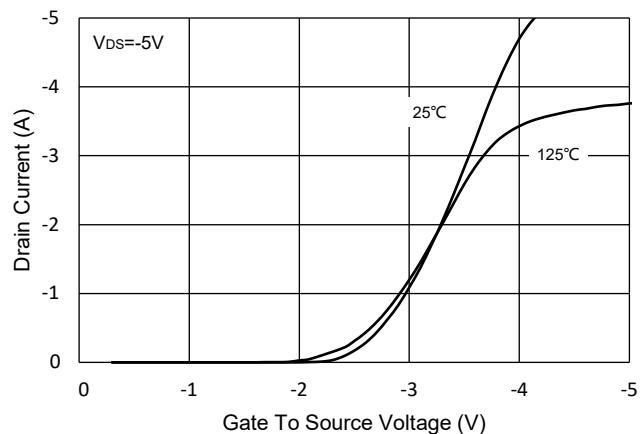


Fig.3 - $R_{DS(ON)}$ - V_{GS}

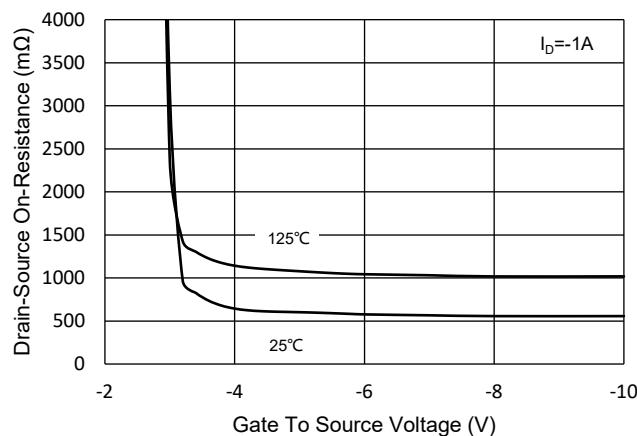


Fig.4 - $R_{DS(ON)}$ - I_D

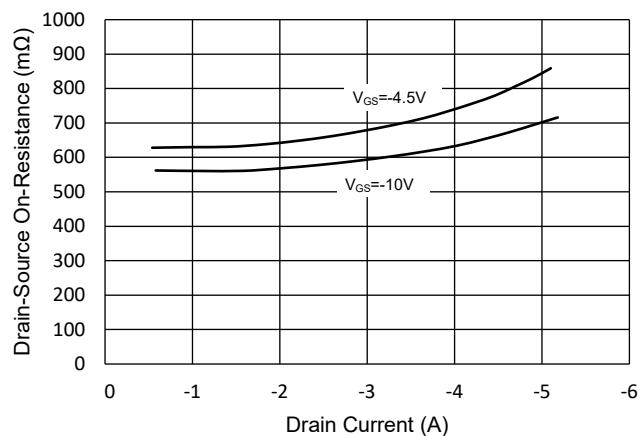


Fig.5 - Capacitance Characteristics

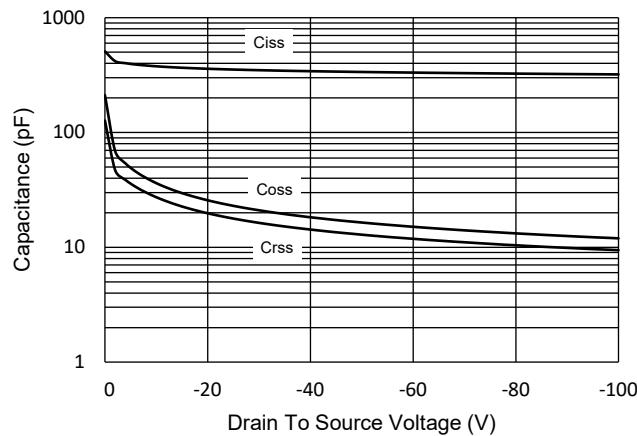
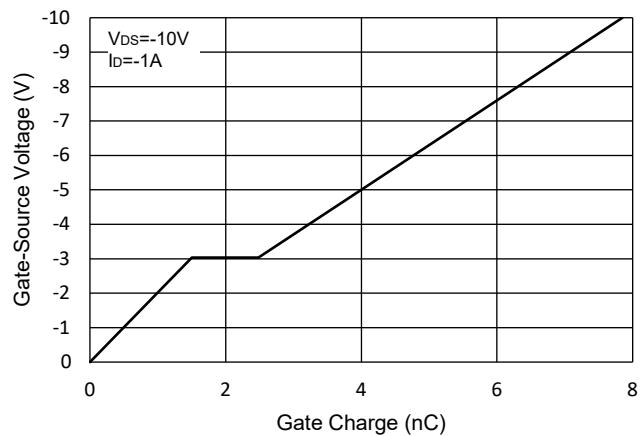


Fig.6 - Gate Charge



Curve Characteristics

Fig.7 - Normalized Threshold Voltage

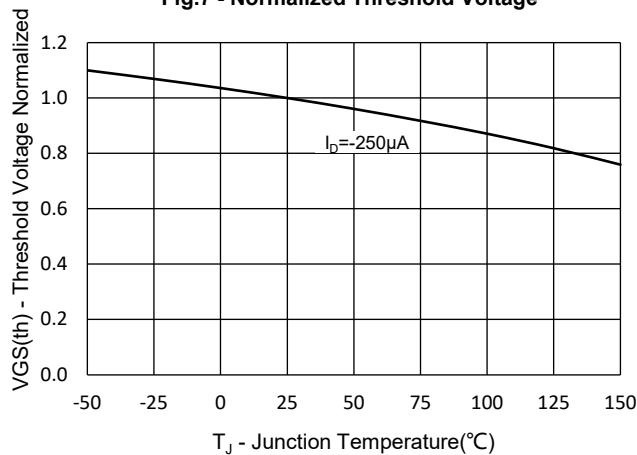


Fig.8 - Normalized On Resistance Characteristics

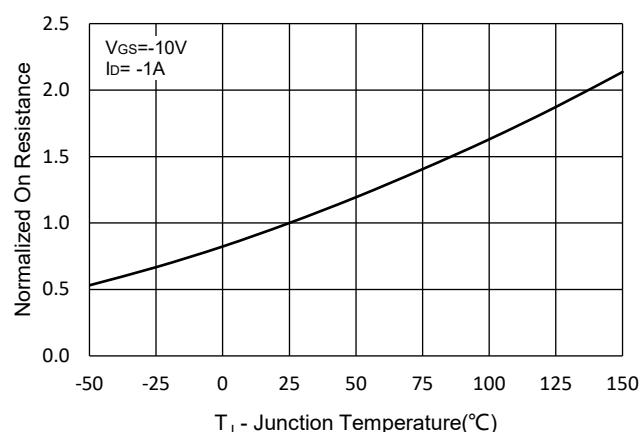


Fig.9 - I_S - V_{SD}

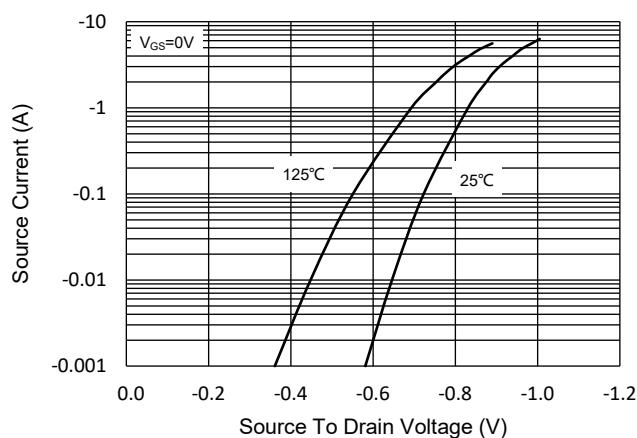


Fig.10 - Drain Current

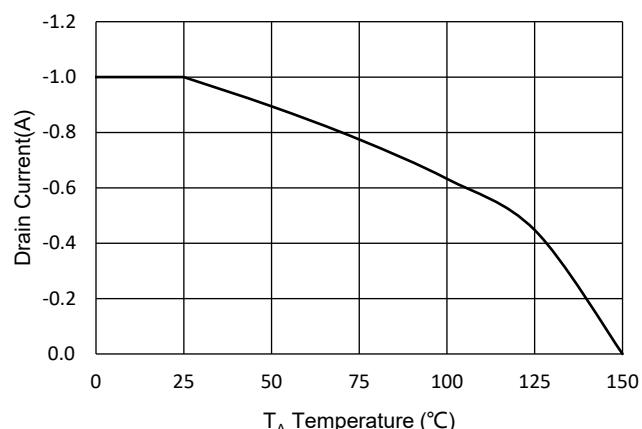
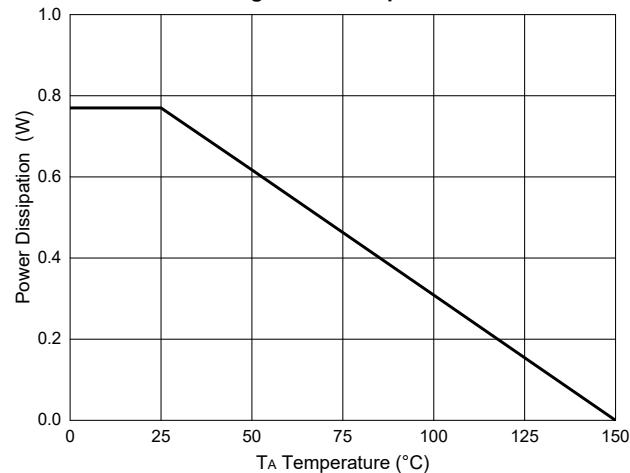


Fig.11-PD Dissipation



Curve Characteristics

Fig. 12 - Safe Operation Area

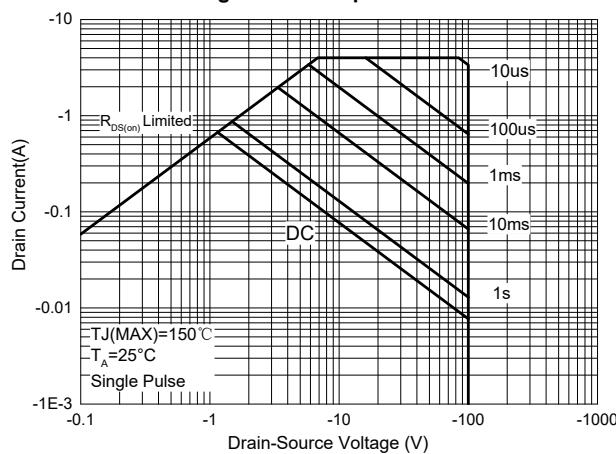
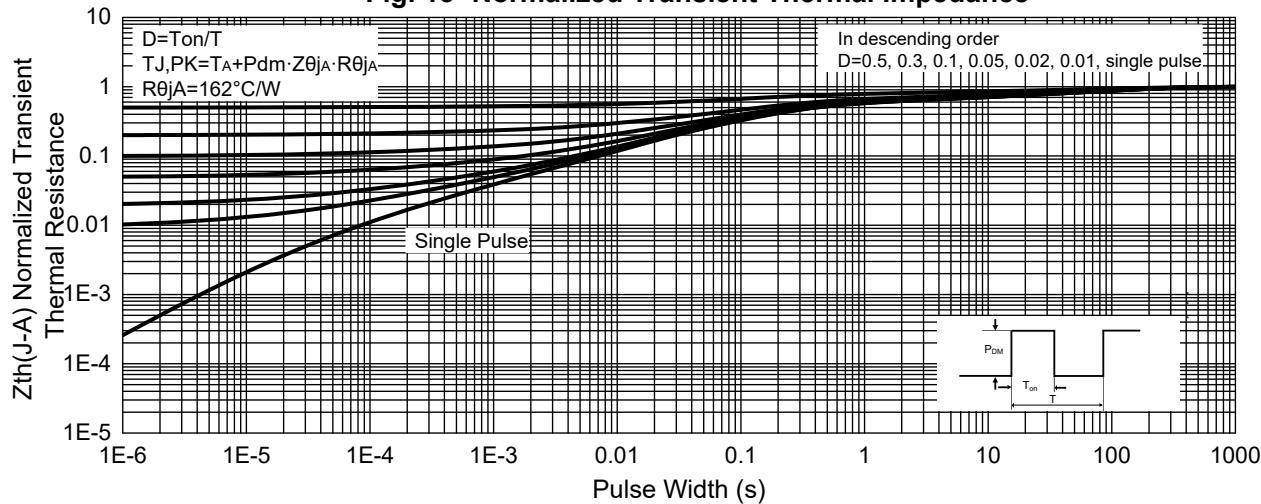


Fig. 13 -Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 3Kpcs/Reel
Part Number-13P	Tape&Reel: 10Kpcs/Reel

For packaging details, go to our website at <https://www.mccsemi.com/pdf/productpackaging/SOT-23%20Package.pdf>

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